

PLASTIC INTEGRATED CIRCUIT PACKAGE AND METHOD  
AND LEADFRAME FOR MAKING THE PACKAGE

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which is a CON of 09/615,107, filed on 7/13/2000, now Patent No 6433277  
FIELD OF THE INVENTION which is a CON of 09/103,760, filed on 6/24/1998, now

The present invention is directed toward an improved plastic package for an integrated circuit die,  
and a method of making such a package.

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BACKGROUND OF THE INVENTION

Integrated circuit die are conventionally enclosed  
in plastic packages that provide protection from  
hostile environments and enable electrical  
15 interconnection between the integrated circuit die and  
printed circuit boards. The elements of such a package  
include a metal leadframe, an integrated circuit die,  
bonding material to attach the integrated circuit die  
to the leadframe, bond wires which electrically connect  
20 pads on the integrated circuit die to individual leads  
of the leadframe, and a hard plastic encapsulant  
material which covers the other components and forms  
the exterior of the package.

The leadframe is the central supporting structure  
25 of such a package. A portion of the leadframe is

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